

CLAIMS

I claim:

- [c1] 1. A method comprising:
- forming a plurality of image sensor die having micro-lenses onto a semiconductor wafer;
- forming a protective layer over said image sensor die;
- dicing said wafer to separate said plurality of image sensor die;
- mounting said image sensor die onto an integrated circuit package; and
- removing said protective layer from said image sensor die.
- [c2] 2. The method of Claim 1 wherein said protective layer is a phenyl resin.
- [c3] 3. The method of Claim 1 wherein said image sensor die uses a ball grid array (BGA) on the underside of said die.
- [c4] 4. The method of Claim 1 further including electrically connecting said image sensor die to said integrated circuit package prior to said protective layer being removed.
- [c5] 5. The method of Claim 1 wherein said dicing is performed prior to any removal of said protective layer.